

## Pch -30V -5A Power MOSFET

$V_{\mathrm{DSS}}$	-30V
$R_{DS(on)}(Max.)$	50m $Ω$
I <sub>D</sub>	-5A
$P_D$	2.0W

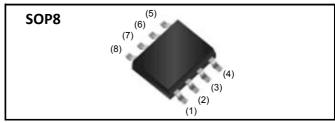
#### Features

- 1) Low on resistance.
- 2) Built-in G-S Protection Diode.
- 3) Small Surface Mount Package (SOP8).
- 4) Pb-free lead plating; RoHS compliant

## Application

DC/DC Converter

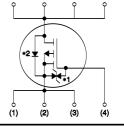
### Outline



### •Inner circuit

- (1) Source(2) Source
- (5) Drain(6) Drain
- (3) Source
- (6) Drain
- (4) Gate
- (8) Drain





Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Typo	Tape width (mm)	12
Туре	Quantity (pcs)	2,500
	Taping code	ТВ
	Marking	RRH050P03

## •Absolute maximum ratings( $T_a = 25^{\circ}C$ )

Parameter	Symbol	Value	Unit
Drain - Source voltage	$V_{DSS}$	-30	V
Continuous drain current	I <sub>D</sub> *1	±5	А
Pulsed drain current	I <sub>D,pulse</sub> *2	±20	Α
Gate - Source voltage	$V_{GSS}$	±20	V
Avalanche energy, single pulse	E <sub>AS</sub> *3	0.2	mJ
Power dissipation	P <sub>D</sub> *4	2.0	W
Power dissipation	P <sub>D</sub> *5	0.65	W
Junction temperature	T <sub>j</sub>	150	°C
Range of storage temperature	T <sub>stg</sub>	−55 to +150	°C

## ●Thermal resistance

Parameter	Symbol	Values			Unit
raiametei	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - ambient	R <sub>thJA</sub> *4	-	-	62.5	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub> *5	-	-	125	°C/W

# •Electrical characteristics( $T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit	
r ai ai ii e lei	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS}$ = 0V, $I_D$ = $-1$ mA	-30	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I <sub>D</sub> = -1mA referenced to 25°C	1	-25	-	mV/°C	
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = -30V, V_{GS} = 0V$	ı	-	-1	μΑ	
Gate - Source leakage current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$	I	ı	±10	μΑ	
Gate threshold voltage	V <sub>GS (th)</sub>	$V_{DS} = -10V, I_{D} = -1mA$	-1	-	-2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{(GS)th}}{\Delta T_{j}}$	I <sub>D</sub> = -1mA referenced to 25°C	-	3.9	-	mV/°C	
		$V_{GS} = -10V, I_D = -5A$	-	36	50		
Static drain - source	<b>.</b> *6	$V_{GS}$ = -4.5V, $I_{D}$ = -2.5A	-	52	72	m()	
on - state resistance	R <sub>DS(on)</sub> 6	$V_{GS} = -4.0V, I_D = -2.5A$	-	58	80	mΩ	
		V <sub>GS</sub> = -10V, I <sub>D</sub> = -5A, T <sub>j</sub> =125°C	ı	45	63		
Gate input resistannce	$R_{G}$	f = 1MHz, open drain	-	9.5	-	Ω	
Transconductance	<b>9</b> fs *6	$V_{DS} = -10V, I_{D} = -5A$	4.0	8.0	-	S	

<sup>\*1</sup> Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw  $\leq 10 \mu s, \, Duty \, cycle \leq 1\%$ 

<sup>\*3</sup> L  $\simeq$  10 $\mu$ H,  $V_{DD}$  = -15V, Rg = 25 $\Omega$ , starting  $T_i$  = 25 $^{\circ}$ C

<sup>\*4</sup> Mounted on a ceramic board (30×30×0.8mm)

<sup>\*5</sup> Mounted on a FR4 (20×20×0.8mm)

# •Electrical characteristics( $T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit
r ai ai ii etei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	850	-	
Output capacitance	$C_{oss}$	V <sub>DS</sub> = -10V	-	120	-	pF
Reverse transfer capacitance	$C_{rss}$	f = 1MHz	-	120	-	
Turn - on delay time	t <sub>d(on)</sub> *6	$V_{DD} \simeq -15V$ , $V_{GS} = -10V$	-	9	-	
Rise time	t <sub>r</sub> *6	I <sub>D</sub> = -2.5A	-	25	-	no
Turn - off delay time	${\rm t_{d(off)}}^{*6}$	$R_L = 6.0\Omega$	-	55	-	ns
Fall time	t <sub>f</sub> *6	$R_G = 10\Omega$	-	30	-	

# •Gate Charge characteristics( $T_a = 25$ °C)

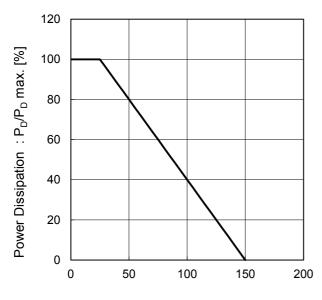
Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	$Q_g^{*6}$	$V_{DD} \simeq -15V$ , $I_D = -5A$ $V_{GS} = -5V$	-	9.2	-	
Total gate charge		$V_{DD}^{\sim} -15V, I_{D} = -5A$ $V_{GS} = -10V$	-	17	-	nC
Gate - Source charge	Q <sub>gs</sub> *6	$V_{DD}^{\sim} -15V, I_{D} = -5A$ $V_{GS} = -5V$	-	2.4	-	
Gate - Drain charge	Q <sub>gd</sub> *6	$V_{GS} = -5V$	-	3.6	-	

# ●Body diode electrical characteristics (Source-Drain)(T<sub>a</sub> = 25°C)

Parameter	Symbol Conditions -		Values			Unit
r arameter			Min.	Тур.	Max.	Offic
Inverse diode continuous, forward current	l <sub>S</sub> *1	T <sub>a</sub> = 25°C	-	-	-1.6	А
Forward voltage	V <sub>SD</sub> *6	$V_{GS} = 0V, I_s = -5.0A$	1	1	-1.2	V
Reverse recovery time	t <sub>rr</sub> *6	I <sub>S</sub> = -5A	1	20	40	ns
Reverse recovery charge	Q <sub>rr</sub> *6	di/dt = 100A / μs	-	15	30	μС

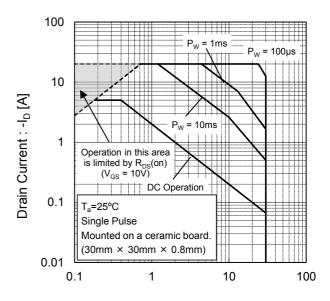
<sup>\*6</sup> Plused

Fig.1 Power Dissipation Derating Curve



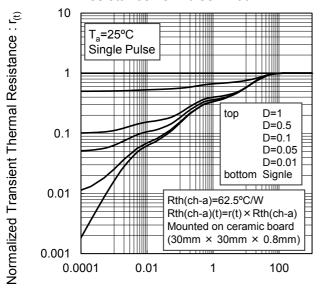
Junction Temperature : Tj [°C]

Fig.2 Maximum Safe Operating Area



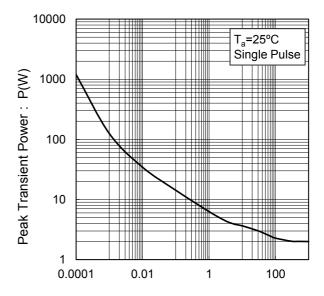
Drain - Source Voltage : -V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width: Pw [s]

Fig.4 Single Pluse Maxmum Power dissipation



Pulse Width : P<sub>W</sub> [s]

Fig.5 Avalanche Current vs Inductive Load

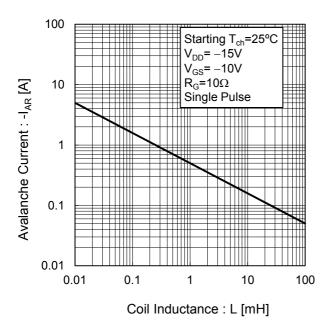


Fig.6 Avalanche Energy Derating Curve vs Junction Temperature

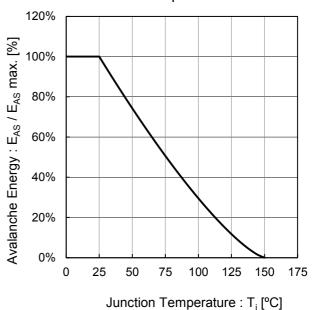
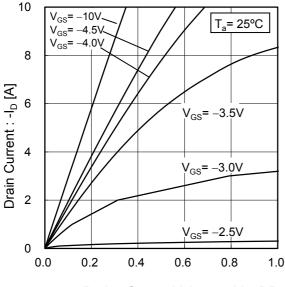
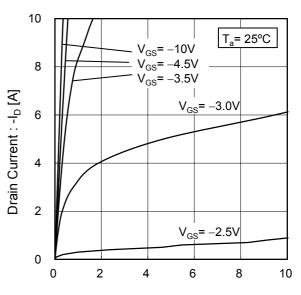


Fig.7 Typical Output Characteristics(I)



Drain - Source Voltage : -V<sub>DS</sub> [V]

Fig.8 Typical Output Characteristics(II)



Drain - Source Voltage : -V<sub>DS</sub> [V]

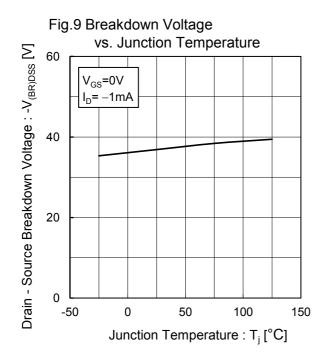


Fig. 10 Typical Transfer Characteristics

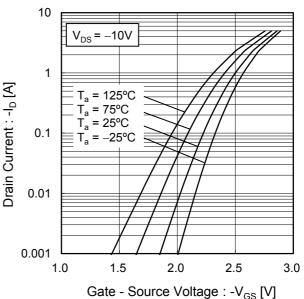


Fig.11 Gate Threshold Voltage vs. Junction Temperature

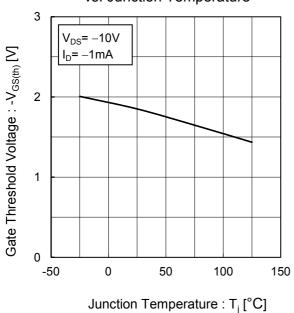


Fig.12 Transconductance vs. Drain Current

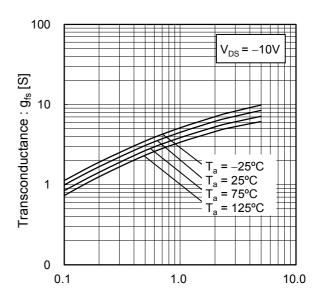


Fig.13 Drain Current Derating Curve

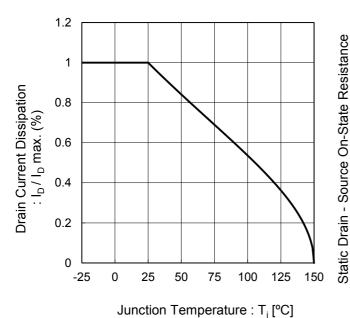
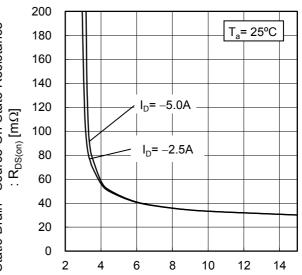


Fig.14 Static Drain - Source On - State Resistance vs. Gate Source Voltage



Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(I)

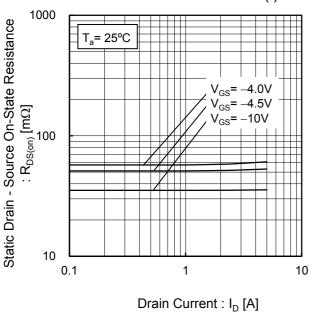
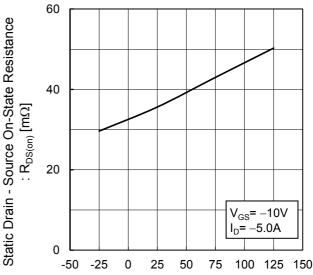


Fig.16 Static Drain - Source On - State
Resistance vs. Junction Temperature



Junction Temperature : T<sub>i</sub> [°C]

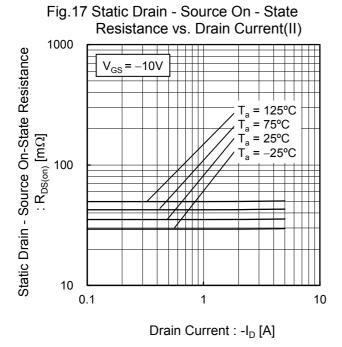


Fig. 18 Static Drain - Source On - State Resistance vs. Drain Current(III)  $T_a = 125^{\circ}\text{C}$   $T_a = 75^{\circ}\text{C}$   $T_a = 25^{\circ}\text{C}$   $T_a = -25^{\circ}\text{C}$   $T_a = -25^{\circ}\text{C}$ 

Fig. 19 Static Drain - Source On - State Resistance vs. Drain Current(IV)

1000  $V_{GS} = -4.0V$   $V_{GS} = -4.0V$  V

Fig.20 Typical Capacitance vs. Drain - Source Voltage

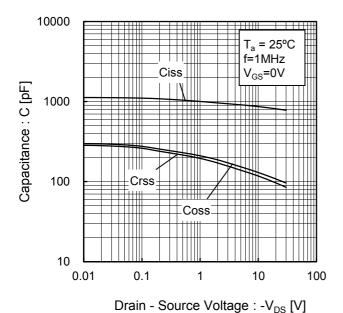


Fig.21 Switching Characteristics

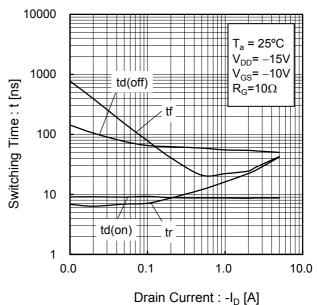


Fig.22 Dynamic Input Characteristics

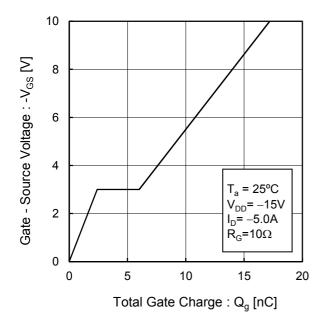
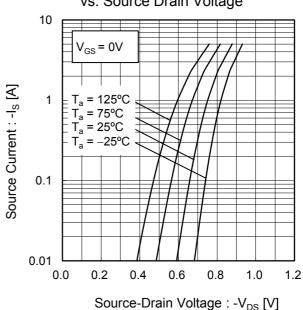


Fig.23 Source Current vs. Source Drain Voltage



## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

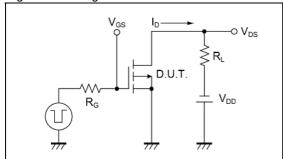


Fig.2-1 Gate Charge Measurement Circuit

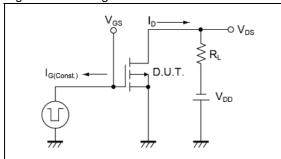


Fig.3-1 Avalanche Measurement Circuit

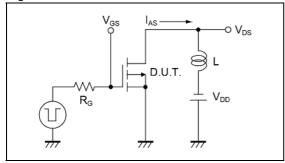


Fig.1-2 Switching Waveforms

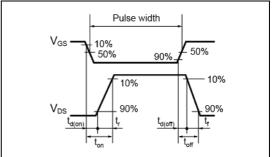


Fig.2-2 Gate Charge Waveform

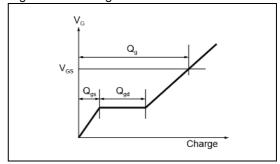
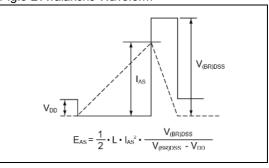
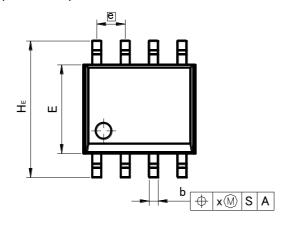


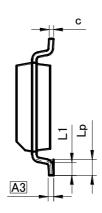
Fig.3-2 Avalanche Waveform

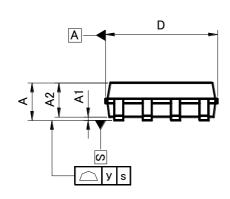


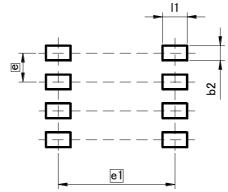
## ●Dimensions (Unit: mm)











## Patterm of terminal position areas

DIM	MILIMI	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	-	1.75	_	0.069	
A1	0.	15	0.0	006	
A2	1.40	1.60	0.055	0.063	
A3	0.2	25	0.0	01	
b	0.30	0.50	0.012	0.02	
С	0.10	0.30	0.004	0.012	
D	4.80	5.20	0.189	0.205	
Е	3.75	4.05	0.148	0.159	
е	1.2	27	0.05		
HE	5.70	6.30	0.224	0.248	
L1	0.50	0.70	0.02	0.028	
Lp	0.65	0.85	0.026	0.033	
х	0.15		0.006		
у	0.	0.10		004	

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
b2	_	0.65	_	0.026
e1	5.	15	0.2	:03
11	_	1.15	_	0.045

Dimension in mm/inches

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CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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